

나노 기술의 이해 (Understanding Nanotechnology)

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Lecture 14.

A brief summary of nanotechnology



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1. Nanotechnology: Definition

- "Research and technology development at the atomic, molecular or macromolecular level in the length scale of approximately 1 - 100 nm range, to provide a fundamental understanding of phenomena and materials at the nanoscale and to create and use structures, devices and systems that have novel properties and functions because of their small and/or intermediate size."

www.nano.gov

- "The development and use of devices that have a size of only a few nanometers." *physics.about.com*

- "Branch of engineering that deals with things smaller than 100 nm (especially with the manipulation of individual molecules)." *www.hyperdictionary.com*

- "Nanotechnology, or, as it is sometimes called, *molecular manufacturing*, is a branch of engineering that deals with the design and manufacture of extremely small electronic circuits and mechanical devices built at the molecular level of matter." *www.whatis.com*

- "The art of manipulating materials on an atomic or molecular scale especially to build microscopic devices." *Miriam Webster Dictionary*

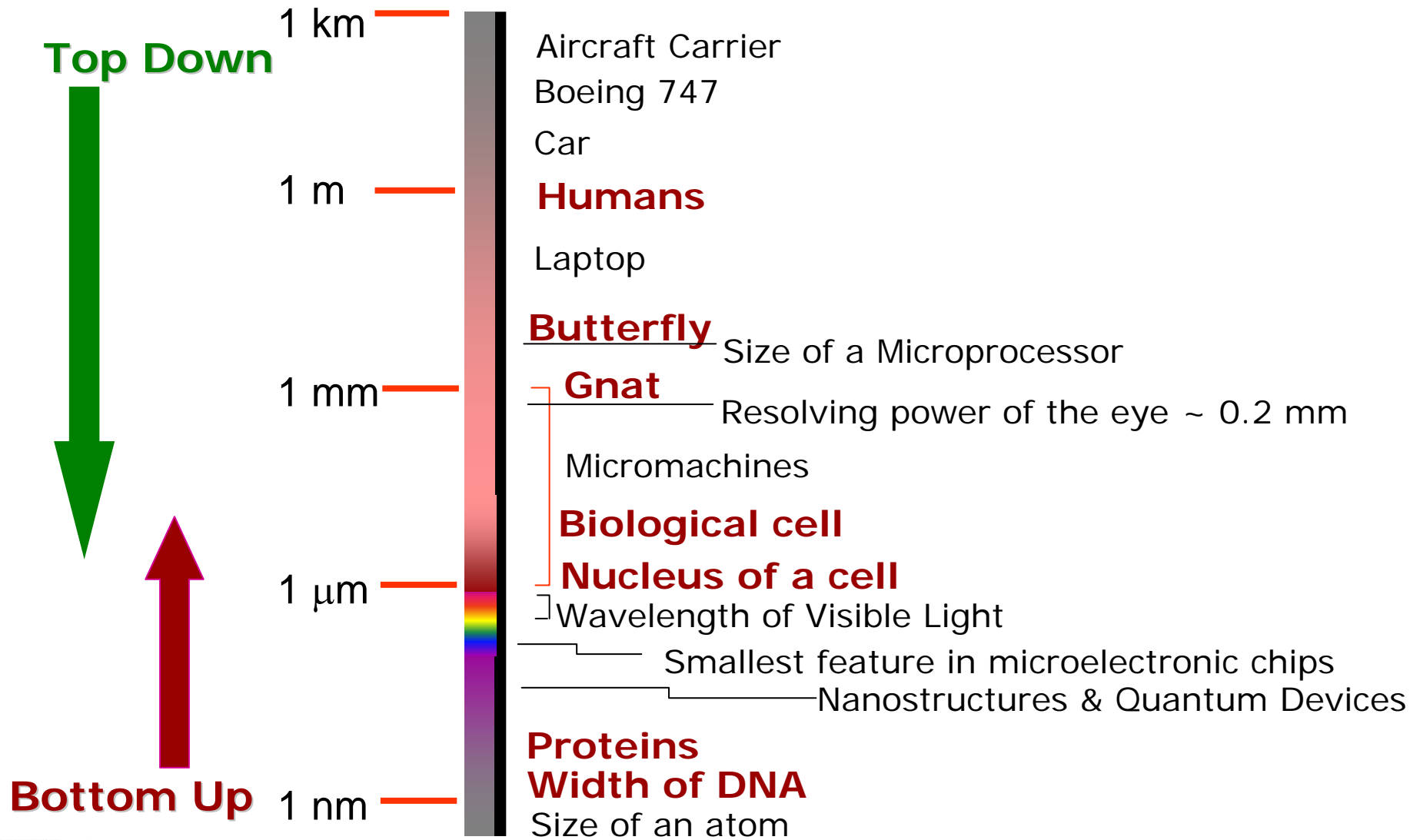


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Perspective of length scale



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Surface vs. Volume

Si has a diamond structure with $a = 5.43 \text{ \AA}$

A Si nanocube 10 nm on a side is composed of:

~6250 unit cells

~50,000 atoms

Each nanocube face is composed of:

~340 unit cells per face

~680 surface atoms per face

Total surface area is:

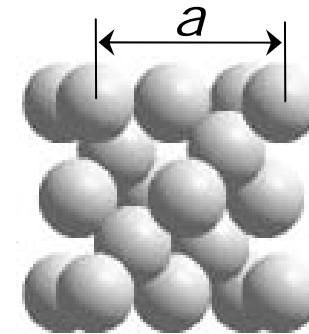
~4080 atoms (~10% surface atoms)

A bulk Si film 1 μm thick on a 10 cm square:

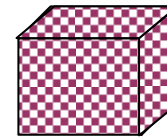
~ 6.3×10^{19} unit cells

~ 5×10^{20} atoms

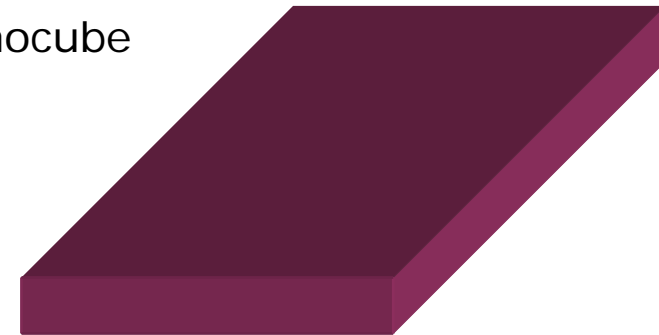
~ 1.4×10^{17} surface atoms (~0.03% surface atoms)



Diamond unit cell



Si nanocube



Bulk Si film

**In a nanoscale material,
the surface/boundary/interface plays an important role!**

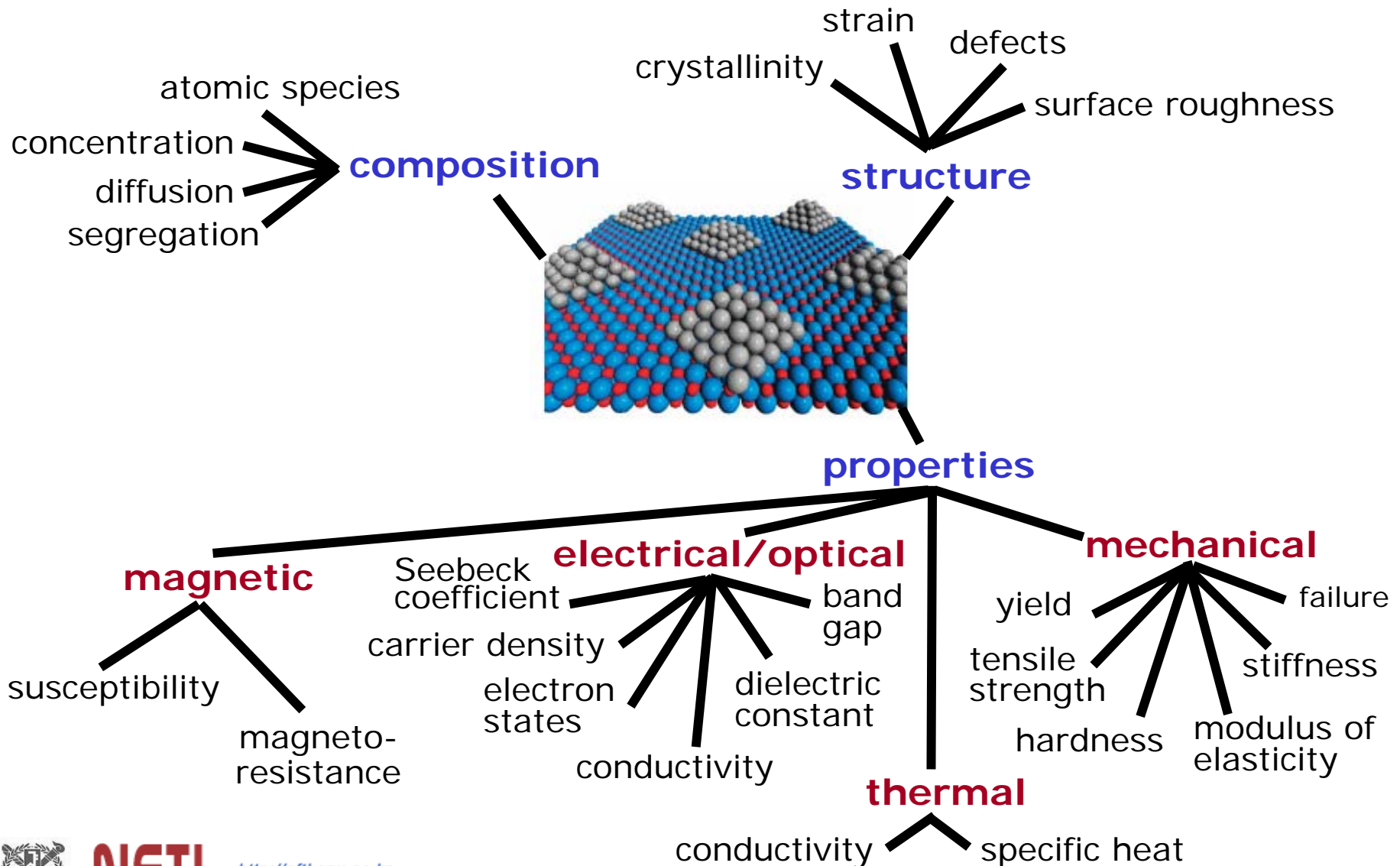


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What can we measure?



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2. Nanotechnology: Nanomaterials

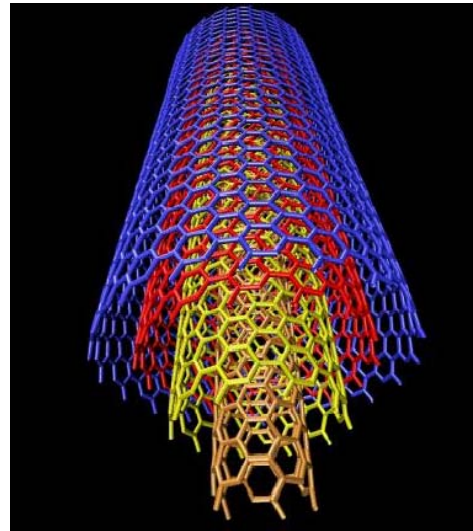
At least one dimension is between 1 - 100 nm

2-D structures (1-D confinement):

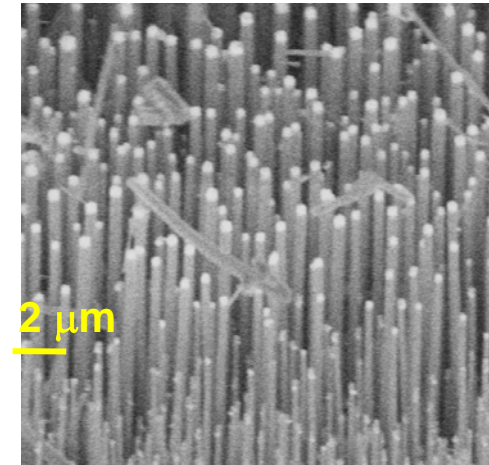
- Thin films
- Planar quantum wells
- Superlattices

1-D structures (2-D confinement):

- Nanowires
- Quantum wires
- Nanorods
- Nanotubes



Multi-wall carbon nanotube



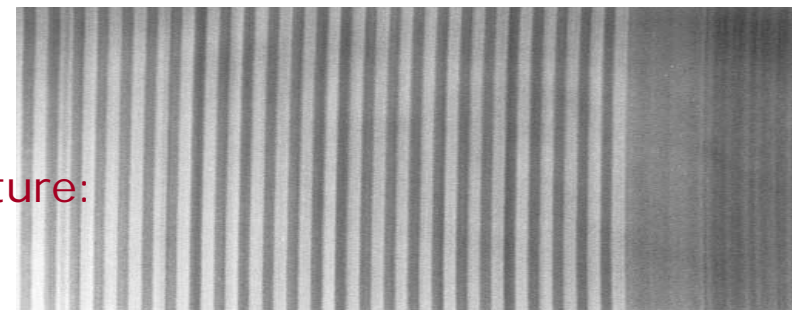
Si Nanowire Array

0-D structures (3-D confinement):

- Nanoparticles
- Quantum dots

Dimensionality, confinement depends on structure:

- Bulk nanocrystalline films
- Nanocomposites



$\text{Si}_{0.76}\text{Ge}_{0.24} / \text{Si}_{0.84}\text{Ge}_{0.16}$ superlattice



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3. Nanotechnology: Nanofabrication

Nanofabrication can generally be divided into two categories based on the approach:

“Top-Down”: Fabrication of device structures via monolithic processing on the nanoscale.

“Bottom-Up”: Fabrication of device structures via systematic assembly of atoms, molecules or other basic units of matter.



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4. Nanotechnology: Nano device

NT-BT:

Nanobiochip (DNA, Protein, Cell chip, Lab on a chip), Drug delivery, Tissue engineering, Nano robots, Biomimetics...

NT-IT:

Nanocomputer (single electron transistor, molecular transistor), Display, Data storage

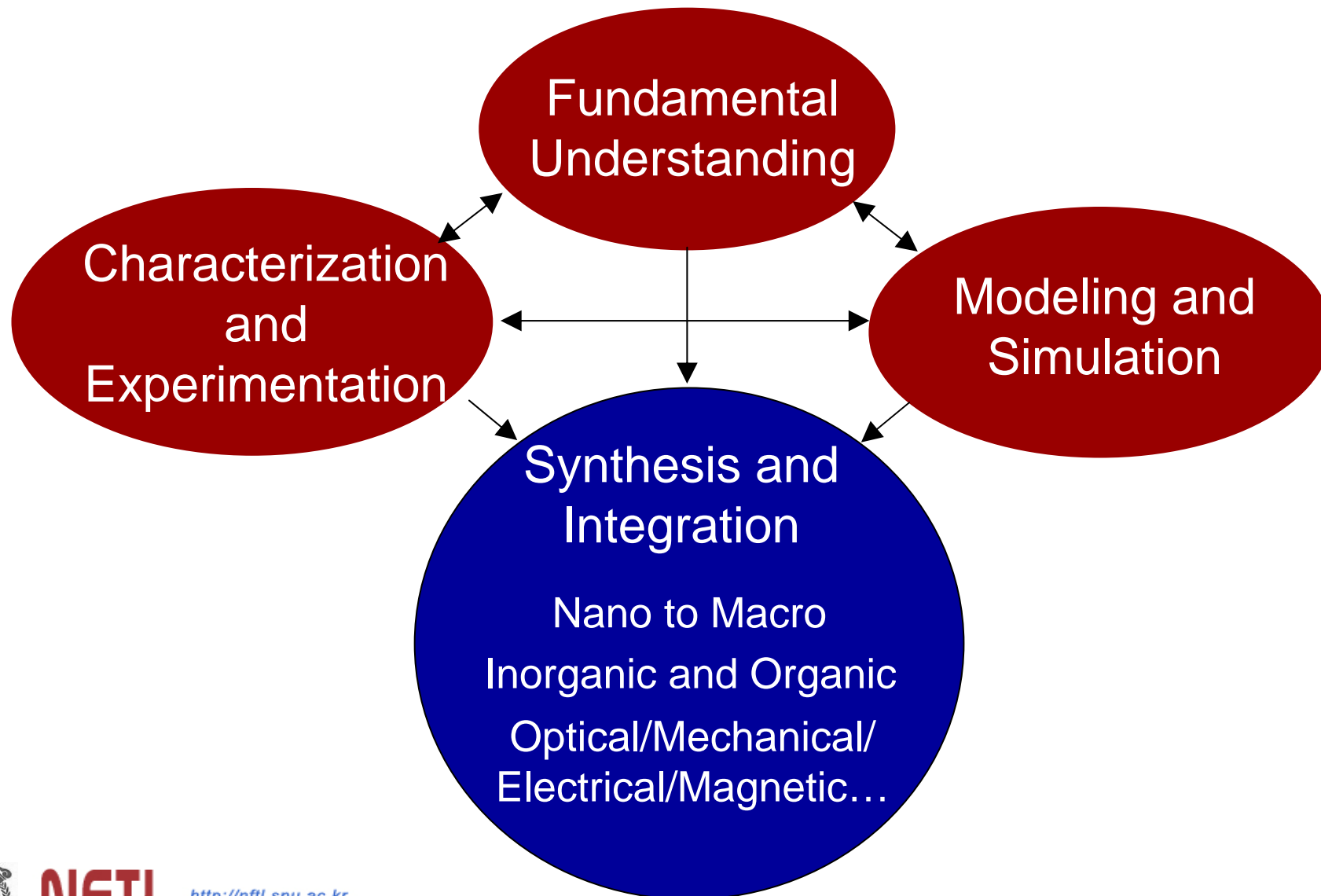


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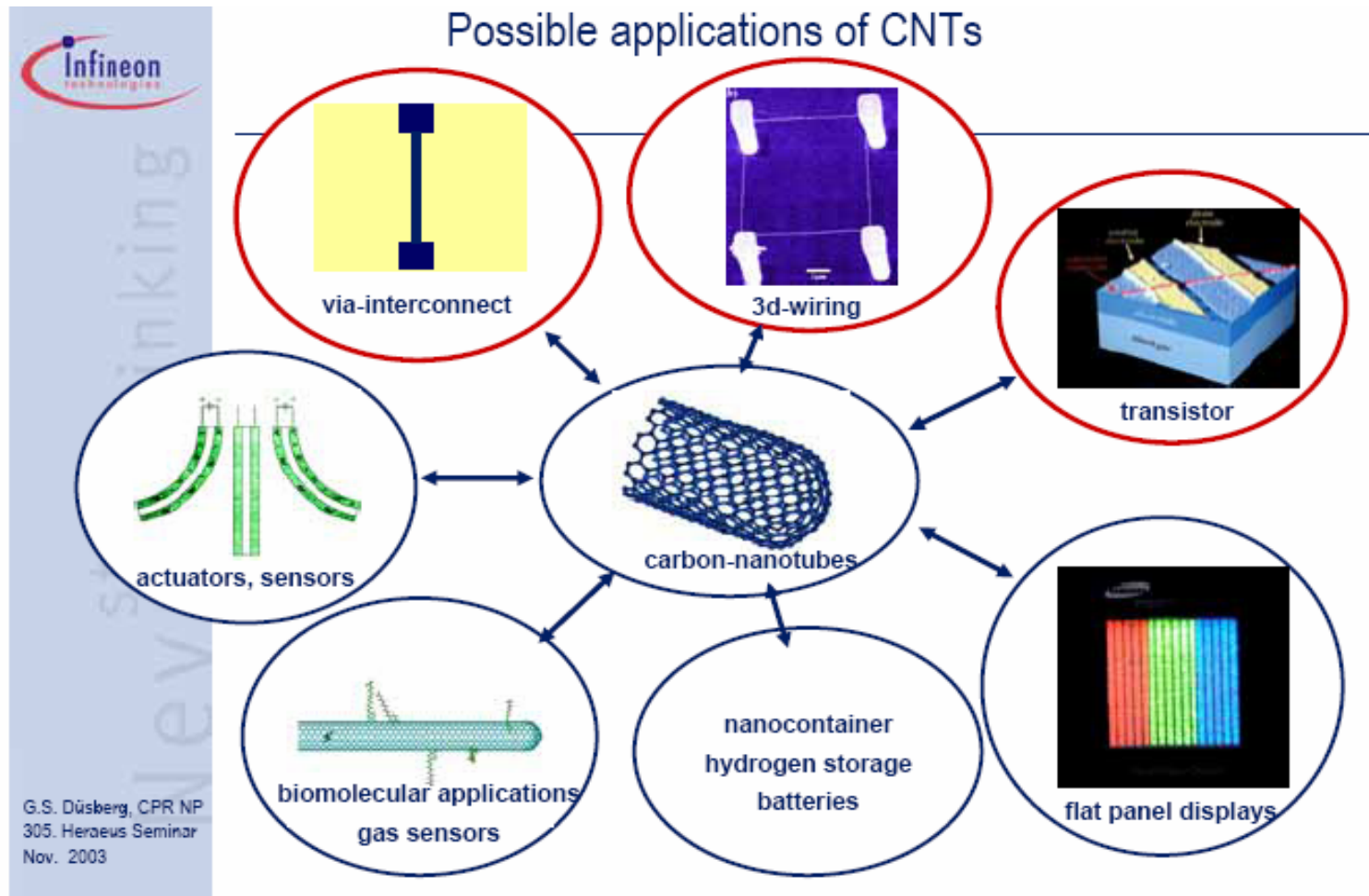
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Development of Nanotechnology



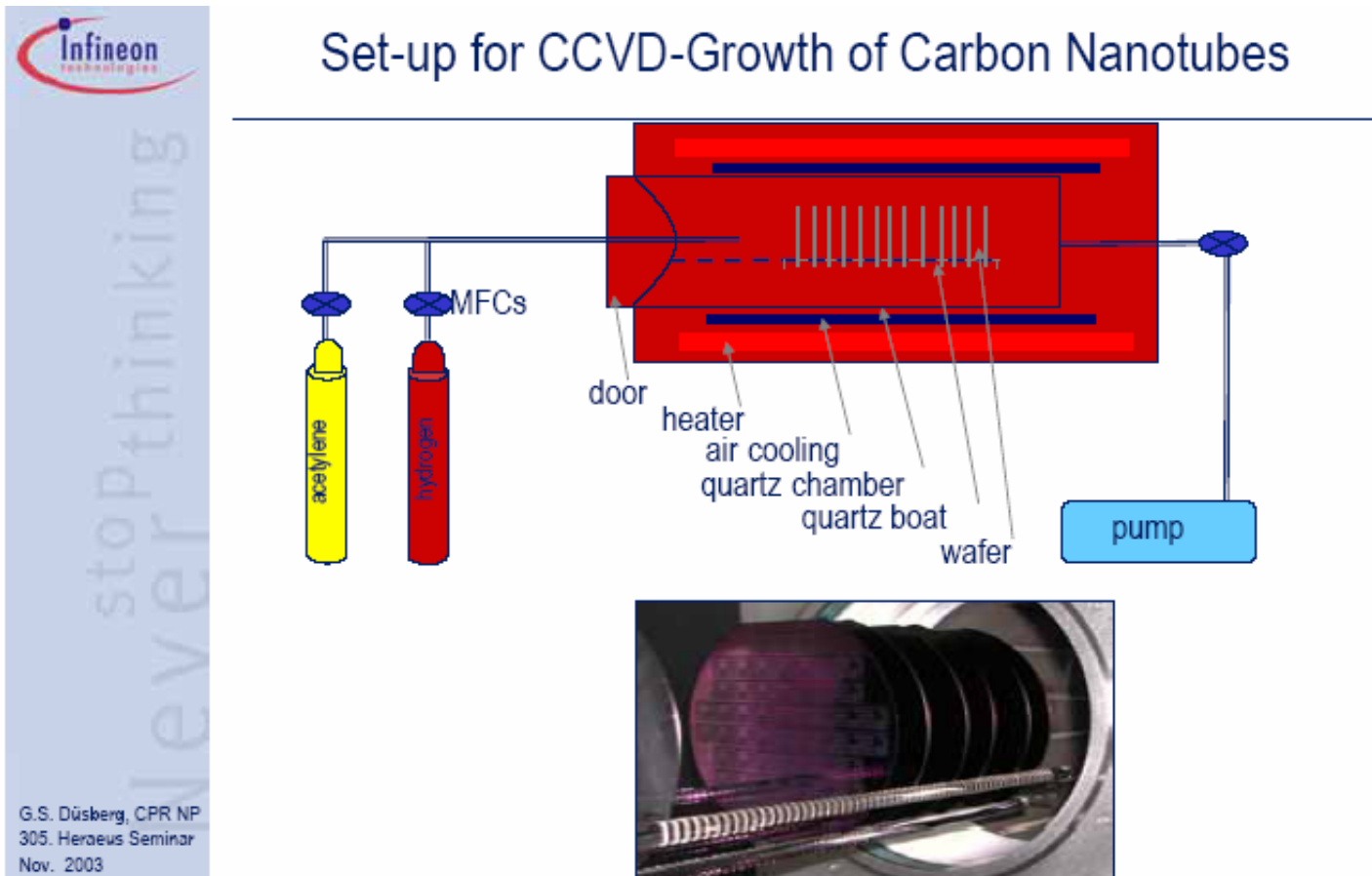
An example of device fabrication

Material? - CNT



An example of device fabrication

Process? – Bottom up + Top down (NT + BT + IT)



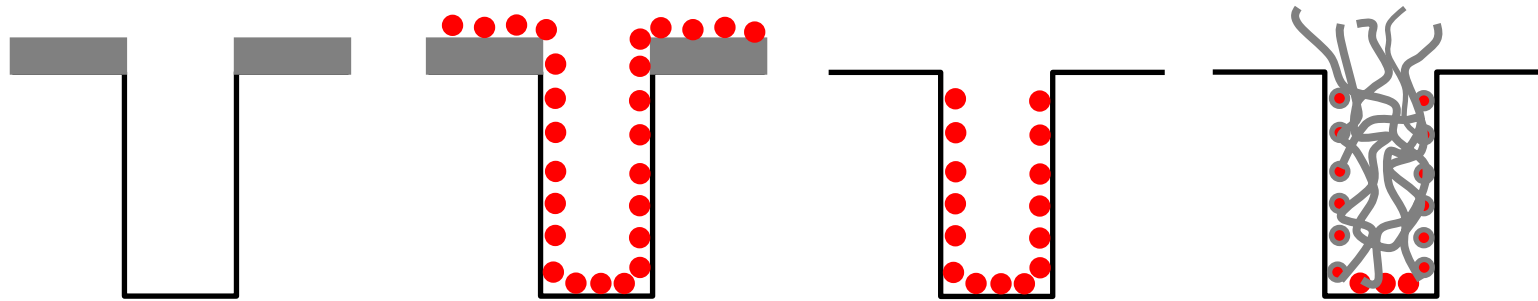
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An example of device fabrication

Process? – Bottom up + Top down (NT + BT + IT)



Via etch

*Sputter
deposit Fe
catalyst*

Lift-off

*MWNT growth by
CVD using
 H_2, C_2H_2 at $700\text{ }^\circ\text{C}$*

*F. Kreupl et al.,
Microelectronic Eng.,
64, 399 (2002).*

